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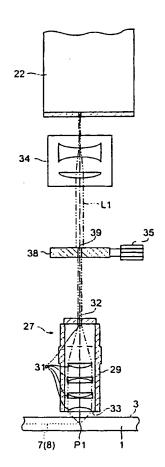
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(54) Title: LASER PROCESSING DEVICE

(54) 発明の名称: レーザ加工装置



(57) Abstract: A laser processing device (20) has a diaphragm member (38) with a first light passage hole (32) and a second light passage hole (39) that has the same diameter as the first light passage hole, and the device is provided on a light path of laser light (L1), which path connects a beam expander (34) and the first light passage hole (32) of a lens holder (29). The diaphragm member (38) is separated from the lens holder (29), so that, even if the diaphragm member (38) is heated by the laser light (L1) cut at a peripheral portion of the second light passage hole (39), heat is prevented from being transmitted from the diaphragm member (38) to the lens holder (29). As a consequence, positional displacement of a light collection point (P1) of the laser light (L1) caused by heating of the lens holder (29) is limited to a small amount.

DM. DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

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FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI 特許 (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

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一 国際調査報告書

2文字コード及び他の略語については、定期発行される各PCTガゼットの巻頭に掲載されている「コードと略語のガイダンスノート」を参照。

(57) 要約:

レーザ加工装置(20)は、ビームエキスパンダ(34)とレンズホルダ(29)の第1の光通過孔(32)とを結ぶレーザ光(L1)の光路上に、第1の光通過孔(32)と同径の第2の光通過孔(39)を有する絞り部材(38)が配置されている。絞り(38)は、レンズホルダ(29)から離間しているため、第2の光通過孔(39)の周囲部分でカットされるレーザ光(L1)により、絞り部材(38)が加熱されても、絞り部材(38)からレンズホルダ(29)への熱伝達が防止される。

したがって、レンズホルダ(29)の加熱によるレーザ光(L1)の集光点 (P1) の位置変動を小さく抑える。

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INTERNATION SEARCH REPORT

Internal application No. O PCT/JP03/15555

A. CLASSIFICATION OF SUBJECT MATTER Int.Cl ⁷ B23K26/04, B28D5/00				
According to International Patent Classification (IPC) or to both national classification and IPC				
B. FIELDS	S SEARCHED			
Minimum documentation searched (classification system followed by classification symbols)				
Int.	C1 ⁷ B23K26/04, B28D5/00			
Jitsu	ion searched other than minimum documentation to the layo Shinan Koho 1922-1996 Li Jitsuyo Shinan Koho 1971-2004	Jitsuyo Shinan Toroku Koho	1996-2004	
Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)				
C. DOCUMENTS CONSIDERED TO BE RELEVANT				
Category*	Citation of document, with indication, where ap	propriate, of the relevant passages	Relevant to claim No.	
A		TONICS KABUSHIKI	1-4	
•	KAISHA), 27 August, 2003 (27.08.03), Full text; all drawings & WO 02/22301 A1			
A	US 6392683 B1 (SUMITOMO HEAV 21 May, 2002 (21.05.02), Full text; all drawings & JP 11-156568 A	Y INDUSTRIES, LTD.),	1-4	
А	Kiyotaka MIURA, Kazuyuki HIRA Shosha ni yoru Garasu Naibu e Keisei", Dai 42 Kai Proceedin Processing Conference, 1997, ISBN:4-947684-15-1	no Hikari Yuki Kozo gs of Laser Materials	1-4	
Further documents are listed in the continuation of Box C. See patent family annex.				
Special categories of cited documents: "A" document defining the general state of the art which is not considered to be of particular relevance "E" earlier document but published on or after the international filing date "L" document which may throw doubts on priority claim(s) or which is cited to establish the publication date of another citation or other special reason (as specified) "O" document referring to an oral disclosure, use, exhibition or other means "P" document published prior to the international filing date but later than the priority date claimed Date of the actual completion of the international search 0.4 March, 2004 (04.03.04) "T" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art document member of the same patent family Date of mailing of the international search report 23 March, 2004 (23.03.04)				
Name and mailing address of the ISA/ Japanese Patent Office		Authorized officer		
Facsimile No.		Telephone No.		

	tion). DOCUMENTS CONSIDERED TO BE RELEVANT	Dalaman da Sa
Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
A	Ken'ichi HAYASHI, "Kotai Laser-Koshuha ni yoru Garasu Kiban eno Naibu Marking", Dai 45 Kai Proceedings of Laser Materials Processing Conference, 1998, pages 23 to 28, ISBN:4- 947684-21-6	1-4
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A	Shuji TAKAOKA, "Gokuusu Handotai Wafer no Dicing ni Saiteki na Steals Dicing Gijutsu no Genri to Tokucho", Denshi Zairyo, 01 September, 2002 (01.09.02), pages 17 to 21	1-4
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